PRODUCT DATASHEET

ATTENTION
OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC SENSITIVE DEVICES

- ▶ Ceramic SMD
- ▶ 3535 2.30t
- ▶ Warm White 2700K

Release Date: 02 April 2025 Version: A1.1

N0W62S87

3535 Ceramic Series

RoHS Compliant

FEATURES:

- **Package:** Top View Ceramic Package
- **Forward Current:** 350~1000mA
- **Forward Voltage (typ.):** 3.0V
- **Luminous Flux (typ.):** 142lm@350mA
- **Colour:** Warm White
- **Colour Temperature (typ.):** 2700K
- **Viewing Angle:** 120°
- **Materials:**
  - Die: InGaN
  - Resin: Silicon (Yellow Diffused)
  - Package: Ceramic
- **Operating Temperature:** -40~+105°C
- **Storage Temperature:** -40~+85°C
- **Electrostatics Discharge (HBM):** 1000V
- **Grouping Parameters:**
  - Forward Voltage
  - Luminous Flux
  - CIE Chromaticity
- **Soldering Methods:** Reflow Soldering
- **MSL Level:** according to J-STD020 MSL 3
- **Packing:** 12mm tape with max.900/reel, ø165mm (6.5'')

APPLICATIONS:

- General Lighting
- Portable Lighting
- Commercial Lighting
- Indoor Lighting
- Architecture Lighting
- High Bay Light

CHARACTERISTICS:

Absolute Maximum Characteristics (T_a=25°C)

Parameter	Symbol	Ratings	Unit
DC Forward Current	I_F	1000	mA
Pulse Forward Current (Duty 1/10, width≤100µS)	I_{PF}	1500	mA
Power Dissipation	P_D	3400	mW
Reverse Voltage	V_R	5	V
Reverse Current @10V	I_R	10	µA
Junction Temperature	T_j	125	°C
Electrostatic Discharge (HBM)	ESD	1000	V
Thermal Resistance (Junction to Solder Point)	$R_{th(j-sp)}$	5	°C/W
Operating Temperature	T_{OPR}	-40~+105	°C
Storage Temperature	T_{STG}	-40~+85	°C
Soldering Temperature	T_{SOL}	230/260 for 10S	°C
Colour Rendering Index	CRI	min. 80 typ. 82	---

1. Rth(j-sp) is the thermal resistance from LED junction to solder point on MCPCB with electrical power.

CHARACTERISTICS:

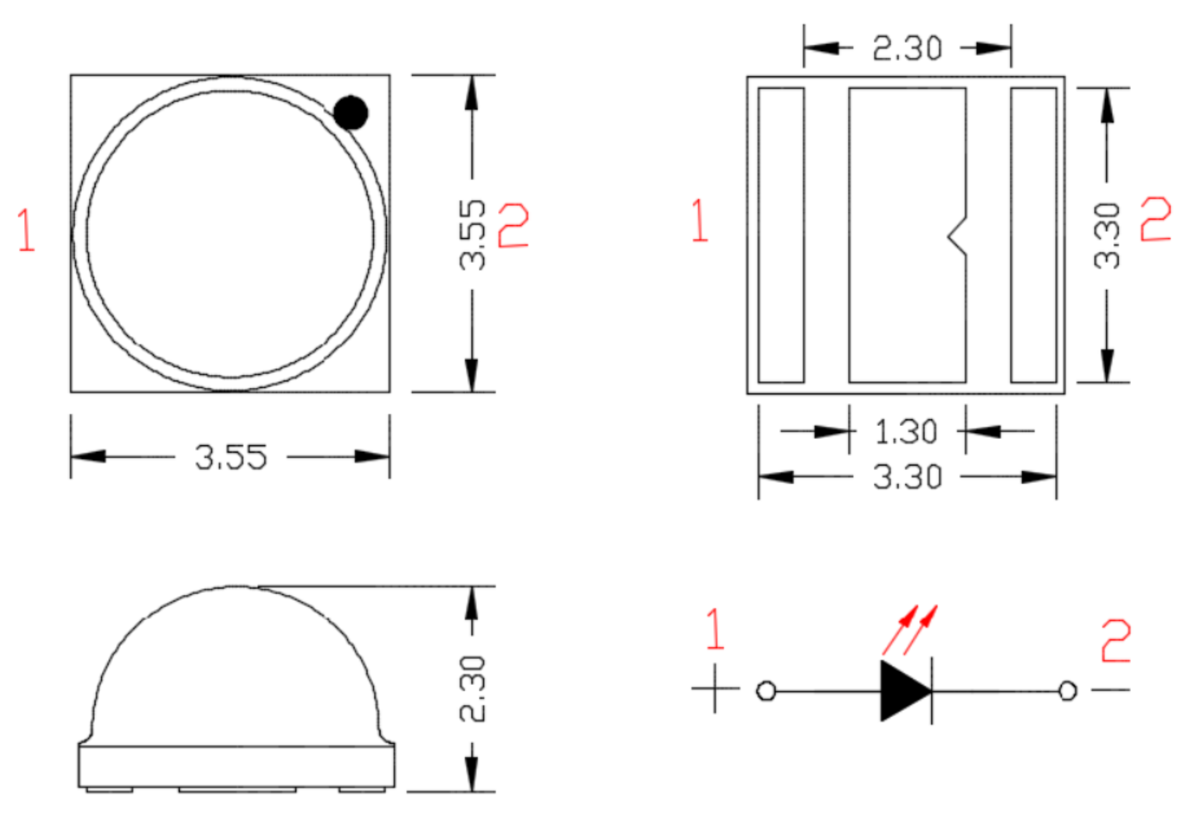
Electrical & Optical Characteristics (T_a=25°C)

Parameter	Symbol	Values			Unit	Test Condition
		Min.	Typ.	Max.		
Forward Voltage	V_F	2.6	3.0	3.4	V	I_F=350mA
Luminous Flux (T_j=25°C)	$Φ_V$	130	142	---	lm	I_F=350mA
		---	275	---		I_F=700mA
Luminous Flux (T_j=85°C)	$Φ_V$	---	132	---	lm	I_F=350mA
		---	246	---		I_F=700mA
Chromaticity Coordinates	X	0.4373	---	0.4813	---	I_F=350mA
	Y	0.3893	---	0.4319		
Colour Temperature	CCT	---	2700	---	K	I_F=350mA
Viewing Angle	$2θ_{1/2}$	---	120	---	deg	I_F=350mA

1. Luminous flux ($Φ_V$) ±10%, Forward Voltage (V_F) ±0.1V, CRI ±2

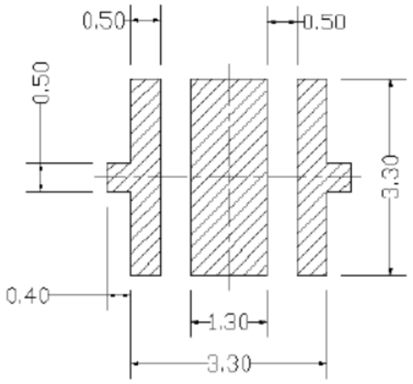
OUTLINE DIMENSION:

Package Dimension:

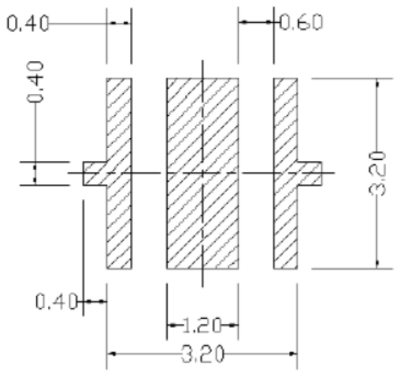


1. All dimensions are in millimetre (mm).
2. Tolerance ±0.2mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



Recommended PCB Solder Pad



Recommended Stencil Pad

1. Dimensions are in millimetre (mm).
2. Tolerance ±0.1mm with angle tolerance ±0.5°.

BINNING GROUPS:

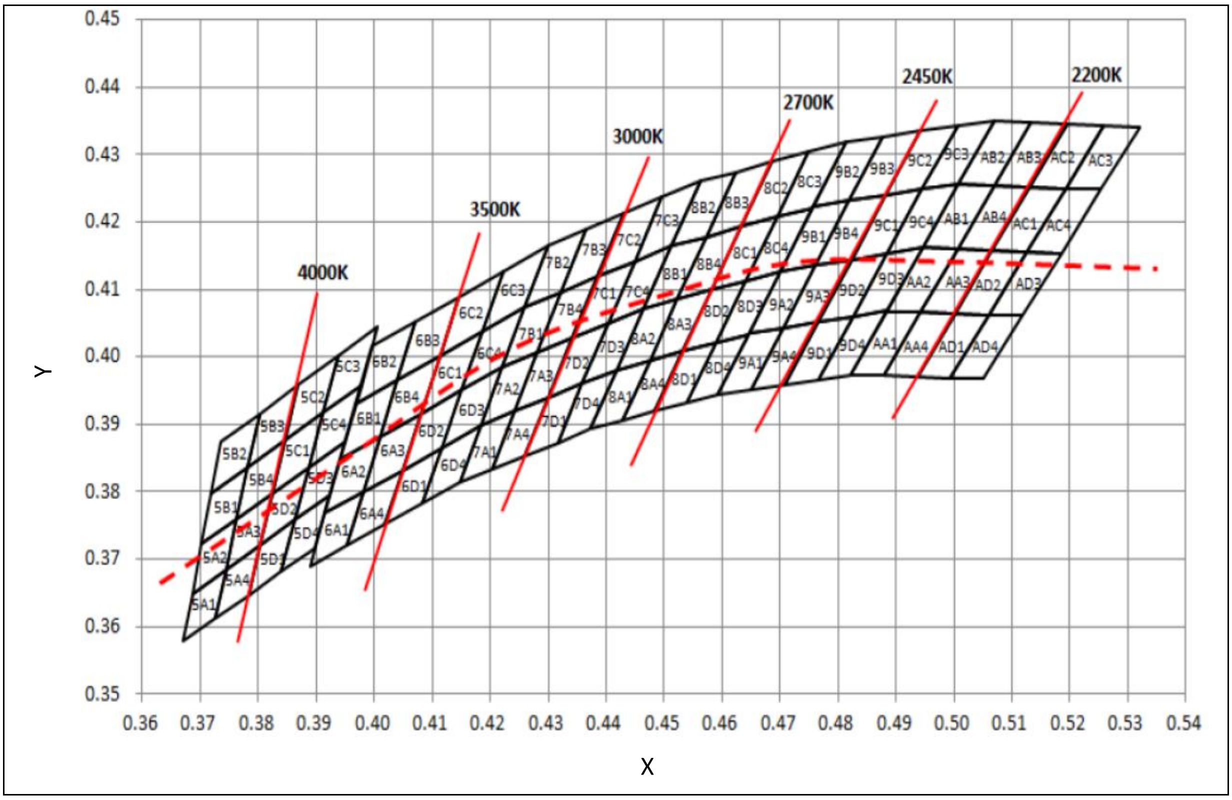
Forward Voltage Classifications (I_F = 350mA):

Code	Min.	Max.	Unit
G3	2.6	2.8	V
H3	2.8	3.0	
J3	3.0	3.2	
K3	3.2	3.4	

Luminous Flux Classifications (I_F = 350mA):

Code	Min.	Max.	Unit
2F	130	139	lm
2G	139	148	
2H	148	156	
2J	156	164	

CIE CHROMATICITY DIAGRAM:



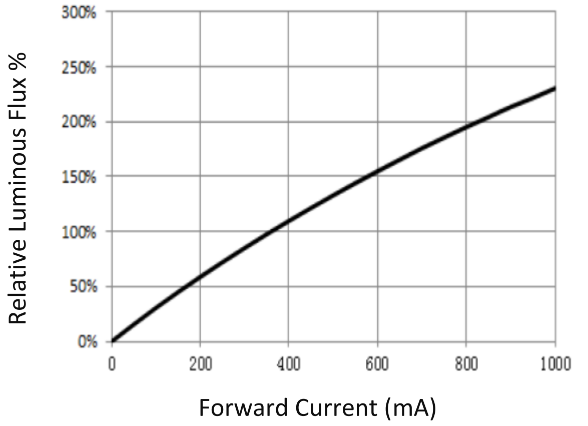
Chromaticity Coordinates Classifications (I_F = 350mA):

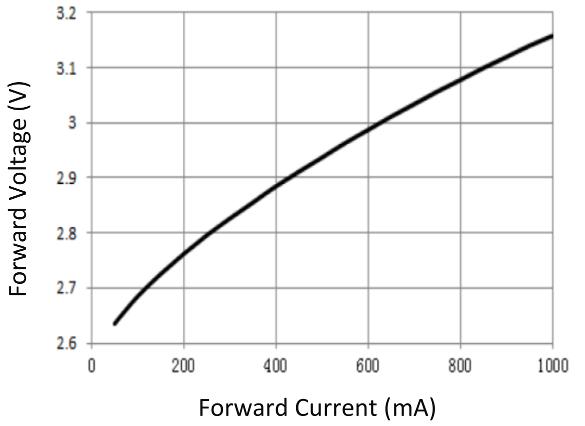
	1		2		3		4	
	X	Y	X	Y	X	Y	X	Y
8A1	0.4373	0.3893	0.4418	0.3981	0.4475	0.3994	0.4428	0.4906
8A2	0.4418	0.3981	0.4465	0.4071	0.4523	0.4085	0.4475	0.3994
8A3	0.4475	0.3994	0.4523	0.4085	0.4582	0.4099	0.4532	0.4008
8A4	0.4428	0.3906	0.4475	0.3994	0.4532	0.4008	0.4483	0.3919
8B1	0.4465	0.4071	0.4513	0.4164	0.4573	0.4178	0.4523	0.4085
8B2	0.4513	0.4164	0.4562	0.4260	0.4624	0.4274	0.4573	0.4178
8B3	0.4573	0.4178	0.4624	0.4274	0.4687	0.4289	0.4634	0.4193
8B4	0.4523	0.4085	0.4573	0.4178	0.4634	0.4193	0.4582	0.4099
8C1	0.4582	0.4099	0.4634	0.4193	0.4695	0.4207	0.4641	0.4112
8C2	0.4634	0.4193	0.4687	0.4289	0.4750	0.4304	0.4695	0.4207
8C3	0.4695	0.4207	0.4750	0.4304	0.4813	0.4319	0.4756	0.4221
8C4	0.4641	0.4112	0.4695	0.4207	0.4756	0.4221	0.4700	0.4126

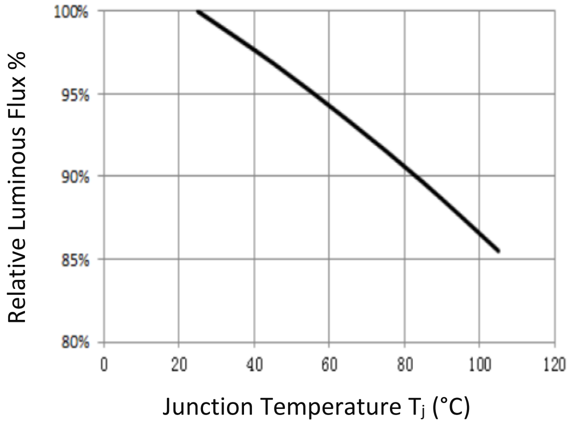
Chromaticity Coordinates Classifications (I_F = 350mA):

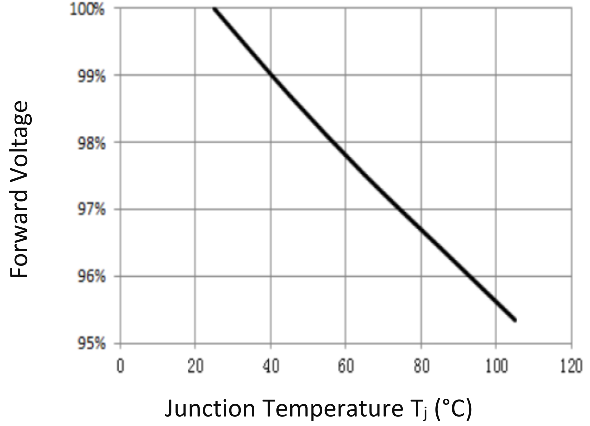
	1		2		3		4	
	X	Y	X	Y	X	Y	X	Y
8D1	0.4483	0.3919	0.4532	0.4008	0.4589	0.4021	0.4538	0.3931
8D2	0.4532	0.4008	0.4582	0.4099	0.4641	0.4112	0.4589	0.4021
8D3	0.4589	0.4021	0.4641	0.4112	0.4700	0.4126	0.4646	0.4034
8D4	0.4538	0.3931	0.4589	0.4021	0.4646	0.4034	0.4593	0.3944

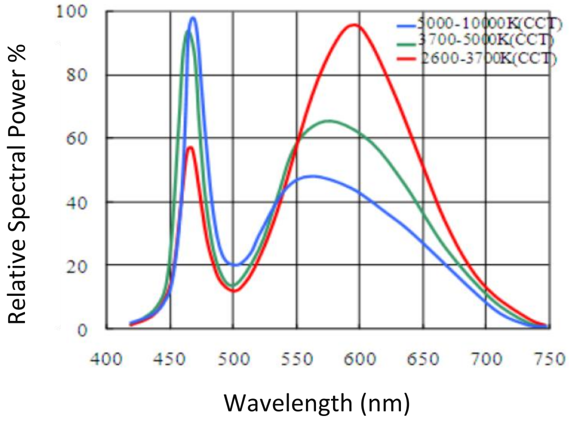
ELECTRO-OPTICAL CHARACTERISTICS:

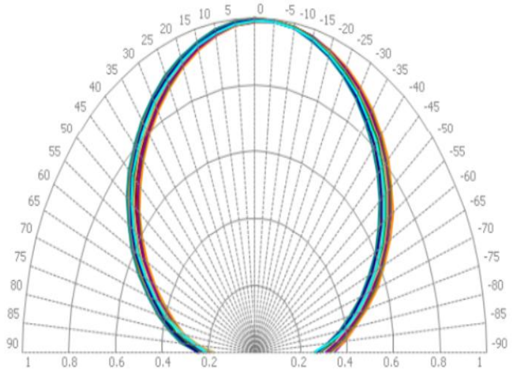

Relative Luminous Flux v.s. Forward Current

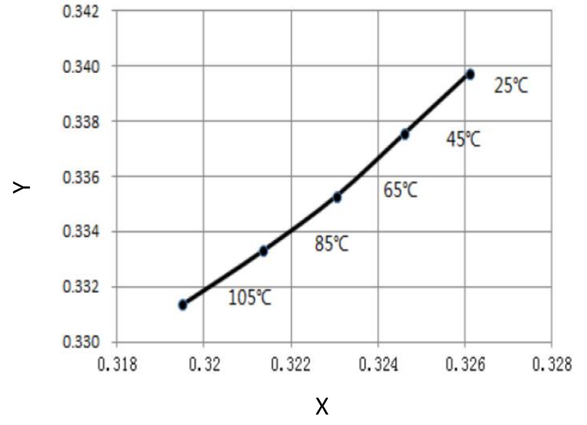
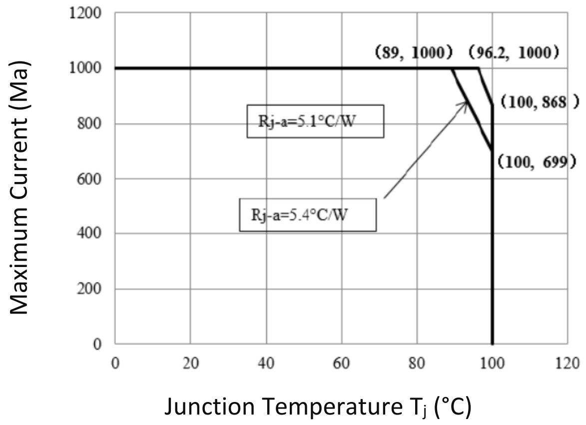

Forward Current v.s. Forward Voltage


Relative Luminous Flux v.s. Junction Temp.


Forward Voltage v.s. Junction Temp.

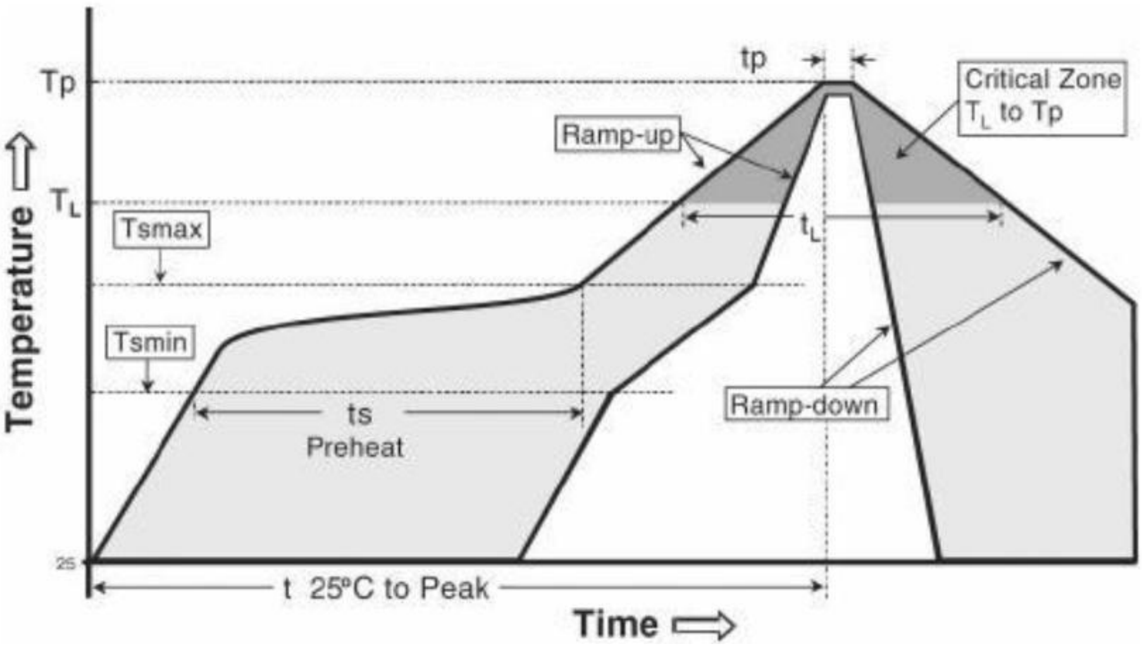

Relative Spectral Power v.s. Wavelength


Directive Radiation

Ambient Temperature v.s. CIE X, Y Shift	Forward Current Derating Curve
	

RECOMMENDED SOLDERING PROFILE:

Reflow Lead-free Solder:



Temperature Min. (T_{smin})	150°C
Temperature Max. (T_{smax})	200°C
Period from T_{smin} to T_{smax}	60-120 seconds
Ramp-up Rate (T_L to T_P)	Max.3°C/second
Liquidous Temperature (T_L)	217°C
Time Maintained above T_L	60-150 seconds
Peak Package Temperature (T_P)	Max.260°C
Time within 5°C of the Specified Classification Temperature T_C	Max.30 seconds
Ramp-down Rate (T_P to T_L)	Max.6°C/second
Time from 25°C to Peak Temperature	Max.8 mins

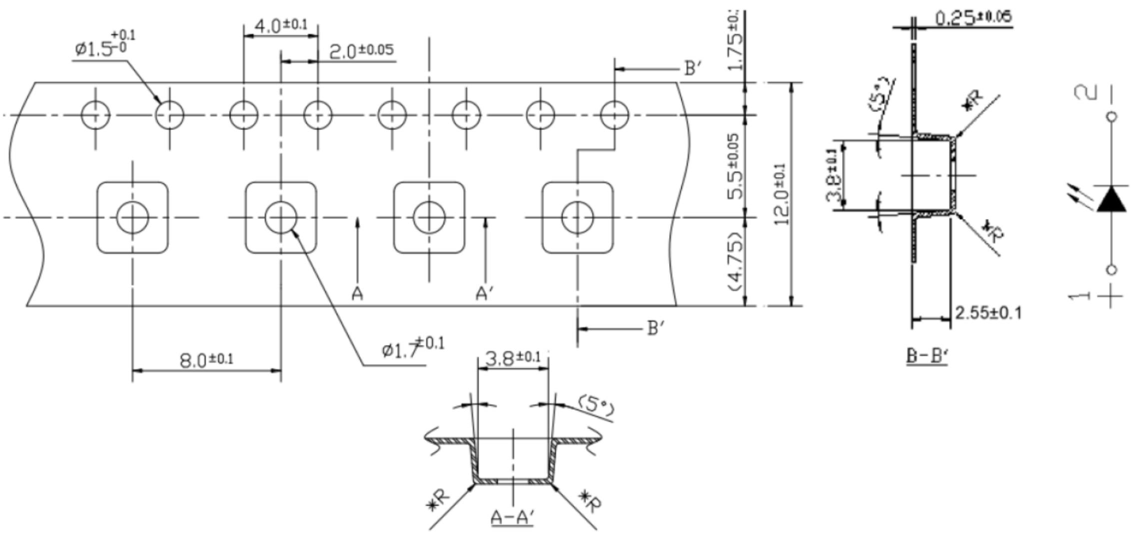
Note:

1. Maximum reflow soldering: 1 time.
2. Before, during, and after soldering, should not apply stress on the components and PCB board.
3. Recommended soldering temperature: 240°C. The maximum soldering temperature should be limited to 260°C for max. 10seconds.

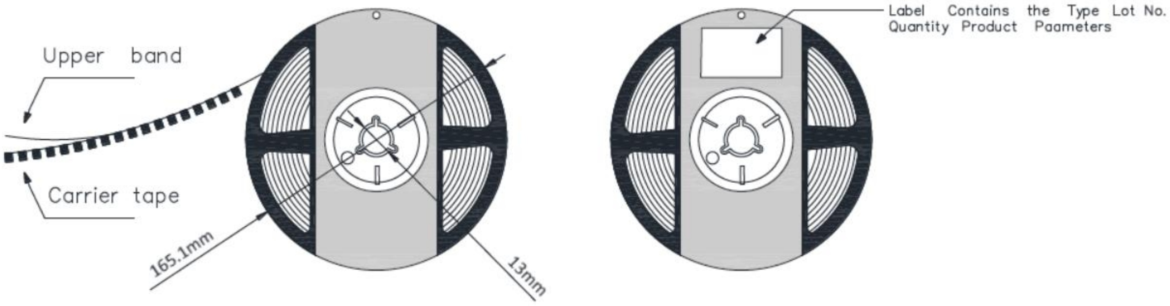
PACKING SPECIFICATION:

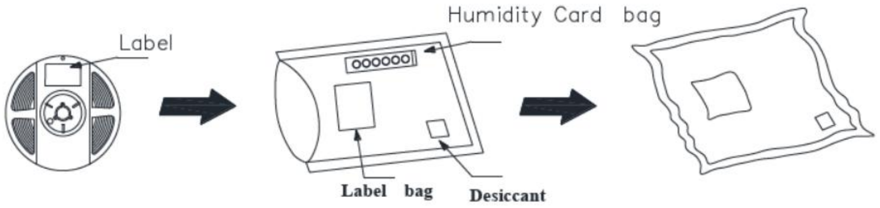
Reel Dimension:

Max.900pcs/reel



1. Cumulative Tolerance: Cumulative Tolerance/10 pitches to be ±0.25mm
2. Adhesion Strength of Cover Tape Adhesion strength to be 0.1-0.7N when the cover tape is turned off from the carrier tape at the angle of 10˚ to the carrier tape.
3.





PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent <10% R.H. and apply baking before use.

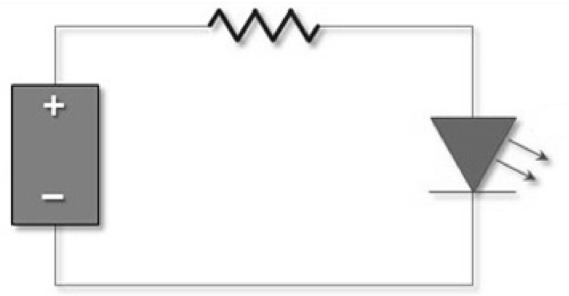
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 60±5°C x 24hrs and <5%RH, taped / reel package.

It’s normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.

REVISION RECORD:

Version	Date	Summary of Revision
A1.0	11/10/2022	Datasheet set-up.
A1.1	02/04/2025	New datasheet format.